

Amendments to Claims

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims

1. - 15. (canceled)

16. (original) A semiconductor topography comprising an upper layer formed conformally upon a non-planar lower layer, wherein an average thickness of the upper layer in a region adjacent to an outer edge of the semiconductor topography is less than an average thickness of the upper layer in a region comprising a center of the topography.

17. (original) The semiconductor topography of claim 16, wherein the region having a lower average thickness extends greater than approximately 3 mm laterally from the outer edge of the semiconductor topography.

18. (original) The semiconductor topography of claim 16, wherein the average thickness of the upper layer in the region adjacent the outer edge is approximately 5% to approximately 30% less than the average thickness of the upper layer in the region comprising the center.

19. - 23. (canceled)